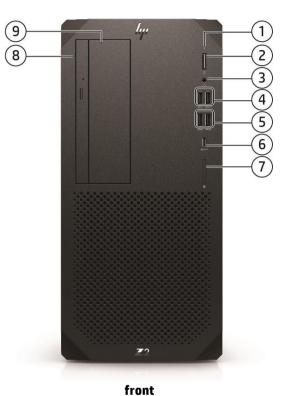
### Overview

## HP Z2 G9 Tower Workstation Desktop PC



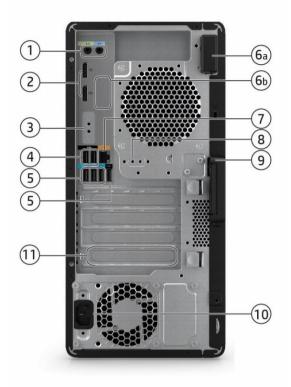
1. HDD Activity LED

- 2. Power button
- 3. Universal audio jack (with CTIA & OMTP headset support)
- 4. (2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A)
- 5. (2) USB-A 10Gbps rate ports

- 6. (1) USB-C<sup>®</sup> 20Gbps port (optional, charge supports up to 5V/3A)
- 7. SD card reader 4.0 (optional)
- 8. Slim ODD bay
- 9. External 5.25" bay



### **Overview**



rear

6.

- 1. (1) Audio Line-in jack (1) Audio Line-out jack
- 2. (2) DisplayPort 1.4 ports
- Flex I/O module: choose one from the following:
   (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual USB-A 5Gbps port, (1) USB-C<sup>®</sup> 10Gbps port (Power Delivery 15W, Alt Mode DisplayPort), (1) 2<sup>nd</sup> 1 GbE LAN, (1) Thunderbolt 3
   with USB-C<sup>®</sup> / USB4 40Gbps \* (cabled to PCIe AIC\*\*) (1) 1Gbps Fiber LC NIC
- 4. (2) Hi-Speed USB-A 480Mbps port
- (2) USB-A 10Gbps ports
   (1) USB-A 5Gbps port
   (1) Hi-Speed USB-A 480Mbps port

\*Maximum speed requires DisplayPort<sup>™</sup> and PCIe aggregation. \*\*Thunderbolt support only in PCI-E slot4.

**NOTE:** Onboard Display support DP1.4/HBR2. Flex I/O module Display support DP1.4/HBR3. Resolution all support up to 5120x3200 24bpp @60Hz.

**Form Factor** 

Tower

#### **Operating Systems**

- Preinstalled:
  - Windows 11 Pro HP recommends Windows 11 Pro<sup>2</sup>
  - Windows 11 Home HP recommends Windows 11 Pro<sup>2</sup>
  - Windows 10 Pro (available through downgrade rights from Windows 11 Pro) <sup>1,2,3</sup>
  - Linux<sup>®</sup>-ready<sup>5</sup>



. (1) 1Gb LAN 2nd serial port (optional)

Hood lock (optional)

(1) WLAN Antenna (optional)

a. Internalb. External

Power connector

### Overview

- Ubuntu<sup>®4,5</sup>
  - Intel 12<sup>th</sup> generation processors will support and preinstall Ubuntu 20.02 and 20.04.
  - $\circ$   $\:$  Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS  $\:$

Web-supported only:

• Windows 10 Enterprise 64<sup>2</sup>

**Supported Version:** 

- HP tested Windows 10, versions 20H2, 21H1, 21H2 and 22H2 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.
- Red Hat<sup>®</sup> Enterprise Linux<sup>®</sup> Workstation 8<sup>6</sup>
- SUSE Linux<sup>®</sup> Enterprise Desktop 15<sup>6</sup>
- Ubuntu<sup>®4,5</sup>
  - Intel 12<sup>th</sup> generation processors will support and preinstall Ubuntu 20.02 and 20.04.
  - o Intel 13<sup>th</sup> generation processors support and preinstall Ubuntu 22.04 LTS

<sup>1</sup> Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

<sup>2</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

<sup>3</sup>This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

<sup>4</sup> Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

<sup>5</sup>A certified preloaded version of Ubuntu<sup>®</sup> 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

<sup>6</sup>For detailed Linux<sup>®</sup> OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix

**NOTE:** Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel<sup>®</sup> and AMD<sup>®</sup> 7th generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

#### Processors Overview<sup>1,3,4,5</sup>

#### Intel 14<sup>th</sup> Generation Processors:

Intel<sup>®</sup> Core<sup>™</sup> i5-14400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.7 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)



### Overview

Intel<sup>®</sup> Core™ i5-14500 (2.6GHz P-Core base frequency, 1.9GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel<sup>®</sup> Core<sup>™</sup> i5-14600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.2GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel<sup>®</sup> Core<sup>™</sup> i5-14600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel<sup>®</sup> Core<sup>™</sup> i7-14700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2Ghz E-Core base frequency, up to 5.3Ghz E-Core base frequency, 33MB L3 cache, 8 P-cores and 12 E-cores, 28 threads)

Intel<sup>®</sup> Core™ i7-14700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.5 GHz P-core Max Turbo frequency, 33MB L3 cache, 8 P-cores and 12 E-cores, 28 threads)

Intel<sup>®</sup> Core<sup>™</sup> i9-14900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads) Intel<sup>®</sup> Core<sup>™</sup> i9-14900K (3.2GHz P-Core base frequency, 2.4GHz E-Core base frequency, up to 4.4GHz E-Core Max Turbo

#### frequency, up to 5.6 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads) Intel 13<sup>th</sup> Generation Processors:

Intel<sup>®</sup> Core<sup>™</sup> i5-13400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.3GHz E-Core Max Turbo frequency, up to 4.6 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads) Intel<sup>®</sup> Core<sup>™</sup> i5-13500 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads) Intel<sup>®</sup> Core<sup>™</sup> i5-13600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel<sup>®</sup> Core™ i5-13600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel<sup>®</sup> Core™ i7-13700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.1Ghz E-Core base frequency, up to 5.1Ghz E-Core base frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel<sup>®</sup> Core<sup>™</sup> i7-13700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads) Intel<sup>®</sup> Core<sup>™</sup> i9-13900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo

frequency, up to 5.2 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel<sup>®</sup> Core<sup>™</sup> i9-13900K (3GHz P-Core base frequency, 2.2GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

#### Intel 12<sup>th</sup> Generation Processors:

Intel<sup>®</sup> Core<sup>™</sup> i9-12900 (1.8GHz E-core base frequency, 5.0 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads) Intel<sup>®</sup> Core<sup>™</sup> i7-12700 (1.6 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads) Intel<sup>®</sup> Core<sup>™</sup> i5-12500 (3.0 GHz P-core base frequency, up to 4.6 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores

Intel<sup>®</sup> Core<sup>™</sup> I5-12500 (3.0 GHz P-core base frequency, up to 4.6 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E-cores, 12 threads)

Intel<sup>®</sup> Core<sup>™</sup> i3-12100 (3.3 GHz P-core base frequency, up to 4.3 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

<sup>1</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

<sup>3</sup> Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

### **Overview**

<sup>4</sup> Intel vPro<sup>®</sup> requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro<sup>®</sup> Essentials and Enterprise vary. See http://intel.com/vpro

<sup>5</sup> Memory will run at 4400 speed (MT/s) in 2DPC within 1DIMM population; memory will run at 4000 speed (MT/s) in 2DPC within 2DIMM of 1 Rank population and memory will run at 3600 speed (MT/s) in 2DPC within 2DIMM of 2 Rank population

<b>Color</b> <b>Convertibility</b> <b>Expansion Slots</b> (see system board section for more details)	Black No Slot 1: PCIe Gen5 x16 Slot 2: PCIe Gen3 x1 - with x4 open end Connector Slot 3: PCIe Gen3 x4 - with x16 Connector
Expansion Bays (see storage section for more details) Front I/O	<ul> <li>Slot 4: PCle Gen3 x4 with open end connector</li> <li>(2) Internal 3.5" bays</li> <li>(1) External 5.25" bay</li> <li>(1) Internal 2.5" bay (for SSD only)</li> <li>(1) Dedicated 9.5mm slim optical disk drive bay</li> <li>(2) USB-A 10Gbps ports (1 charge port supports up to 5V/2.1A), (2) USB-A 10Gbps ports, (1) USB-C</li> <li>20Gbps eport (charge supports up to 5V/3A, optional), (1) SD card reader (optional), (1) universal audio jack</li> </ul>
Internal I/O [5]	(1) Hi-Speed USB 480Mbps header for SD card reader (1) serial port available with header (1) serial and PS/2 available with header
Rear I/O	(2) DisplayPort 1.4 ports, (1) Audio Line out, (1) Audio Line in, (1) 1GbE LAN, (3) Hi-Speed USB 480Mbps ports, (2) USB-A 10Gbps ports, (1) USB-A 5Gbps port, (1) serial (optional), (1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, USB-C <sup>®</sup> 10Gbps port (Power Delivery 15W, Alt Mode Display Port), (1) Dual USB-A 5Gbps port, (1) 2nd 1GbE LAN, (1) Thunderbolt 3 with USB4 USB-C <sup>®</sup> 40Gbps (cabled to PCIe AIC)*, (1) 1Gbps Fiber LC NIC
Optional I/O	Flex IO* – choose one of the following options: (1) DisplayPort™ 1.4 port, (1) HDMI 2.0b, (1) VGA,(1) 2nd 1GbE LAN, (1) 1Gbps Fiber LC NIC, (1) Dual USB-A 5Gbpsport ,(1) USB -C® 10Gbps port (15W USB Power Delivery, Alt Mode DisplayPort™), (1) Thunderbolt™ 3 with USB4 USB-C® 40Gbps port (cabled to PCIe® AIC**);
	Front – (1) USB-C <sup>®</sup> 20Gbps port (charging), (1) SD card reader;
	Front – choose one of the following options: (1) USB-C <sup>®</sup> 20Gbps (charging), (1) SD 4.0 card reader Rear –(1) serial;
	*About Thunderbolt compatibility, please refer to the FAQ of Thunderbolt community. https://www.thunderbolttechnology.net/tech/faq
	**Flex IO port and PCIe slot 4 will be occupied when Thunderbolt is installed.
Interfaces Supported On-board RAID Support	SD card reader (optional) SATA and NVME RAID 0 Striped Array SATA RAID and NVME RAID 1 Mirror Array



### Overview

Chassis Dimensions (H x W x D)	H: 14" [356mm] W: 6.7" [169mm] D: 15.2" [385mm]
Packaged Dimensions	H: 20.39" (518mm) W: 11.61" (295mm) D: 19.29" (490mm)
<b>Rack Dimensions</b>	40
Weight	Exact weights depend upon configuration (System weight only). Starting at 6.2kg (13.7lbs.)
Temperature	Operating: 5° to 35° C (40° to 95° F) Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
Humidity	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
Maximum Altitude (non- pressurized) <sup>6</sup>	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet)
	Maximum operating temperature is reduced as altitude increases. See Temperature for details.
Power Supply	700W wide-ranging, active Power Factor Correction, 92% Efficiency with two 6+2 graphics power connectors. 500W wide-ranging, active Power Factor Correction, 90% Efficiency. 450W wide-ranging, active Power Factor Correction, 90% Efficiency. 350W wide-ranging, active Power Factor Correction, 92% Efficiency.
	<b>NOTE:</b> The Power Supply Efficiency Report for the 700W 92% Efficiency, 500W 90% Efficiency, 450W 90% Efficiency and 350W 92% Efficiency Power Supply may be found at the following links:
	700W PSU:
	https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
	500W PSU:
	LiteOn 500W PSU Efficiency Report
	Delta 500W PSU Efficiency Report
	450W PSU:
	https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2
	350W PSU:
	AcBel 350W PSU (SFF) Efficiency Report AcBel 350W PSU (Custom) Efficiency Report
	Delta 350W PSU Efficiency Report
Backup Devices	For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup System offerings, please visit http://www.hp.com/go/connect
Chipset	Intel® W680 chipset
Memory	4 DIMM slots, supporting up to 128GB ECC/non-ECC, DDR5 4800 MT/s speed depending on the system configuration



### **Supported Components**

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ036AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	LQ037AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Y	Y	QB576AA
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	WOR10AA
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	2Z274AA
	4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	K4T76AA
	8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	2Z273AA
	12TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Y	Y	5S461AA
	500GB SATA 7.2K SED HDD	Y	Y	D8N29AA
	NOTE: For internal bay install, HDD option kits require sepa	arato nurchaso c	of 67911600	HP 72 Tower

**NOTE:** For internal bay install, HDD option kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 6Z9U6AA HP Z2 Tower HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

#### **PCIe Solid State Drives**

HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201G0AA/AT
HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit	Y	Y	201F9AA
HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201F5AA/AT
HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit	Y	Y	201F8AA
Z Turbo 1TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A3AA/AT
Z Turbo 2TB 2280 PCIe-Gen4x4 Self Encrypted OPAL2 TLC M.2 Z2 SSD	Y	Y	223A4AA/AT
256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Y	Y	4M9Z1AA
512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Y	Y	4M9Z2AA
1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 SSD Module	Y	Y	4M9Z3AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Y	Y	5S492AA
Z Turbo 2TB PCIe-4x4 TLC SSD Module	Y	Y	38T75AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Y	Y	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T79AA
Z Turbo 512GB PCIe-4x4 TLC SSD Module	Y	Y	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	38T81AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Y	Y	5S496AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Y	Y	5S497AA
Z Turbo 4TB 2280 PCIe-4x4 SED 0PAL2 TLC M.2 Z2 Kit SSD	Y	Y	5S498AA
<b>NOTE:</b> For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes	s. Actual fo	matted c	apacity is less.

Up to 36GB of system disk (for Windows) is reserved for system recovery software. **NOTE:** PCIe M.2 SSD Kit SKUs include a heatsink. PCIe M.2 SSD Module SKUs do not include a heatsink.



## **Supported Components**

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	Support Notes
<b>Graphics Cable Adapters</b>	HP DisplayPort To HDMI True 4k Adapter	Ŷ	Ŷ	2JA63AA		
	HP Single miniDP-to-DP Adapter Cable	Y	Y	2MY05AA		
	HP DisplayPort To DVI-D Adapter	Y	Y	FH973AA		
	HP DisplayPort To DVI Adapter (Bulk 90)	Y	Y	FH973A6		
			Y	AS615AA/		
	HP DisplayPort To VGA Adapter	Y		AT		
	HP DisplayPort to VGA Adapter Bulk		Y			
	Qty.90)	Y		AS615A6		
	HP DisplayPort To VGA Adapter	Y	Y	F7W97AA		
	HP USB-C to DisplayPort Adapter	Y	Y	4SH08AA		
	HP USB-C to HDMI Adapter	Y	Y	4SH07AA		
	HP USB-C to VGA Adapter	Y	Y	4SH06AA		
Entry 3D	NVIDIA <sup>®</sup> T400 4 GB Graphics <sup>2</sup>	Y	Y	5Z7E0AA/ AT	2	1
	NVIDIA® T400E 4 GB 4mDP Graphics	Y	Y	А4НРЗАА	2	1
	NVIDIA RTX A400 4 GB 4mDP Graphics	Y	Y	9U277AA	2	1
	NVIDIA <sup>®</sup> T600 4 GB Graphics <sup>1</sup>	Ν	Y	340K9AA	2	1
	AMD Radeon Pro WX 3200 4GB	Y	Y	6YT6*AA/ AT	1	1
	AMD Radeon RX 6400 4 GB DH DP+HDMI Graphics	Ν	Y	6Q3U4AA/ AT	1	1
Mid-range 3D	NVIDIA <sup>®</sup> T1000 4 GB Graphics	Y	Y		2	1
	NVIDIA <sup>®</sup> T1000 8 GB Graphics	Y	Y	5Z7D8AA/ AT	2	1
	NVIDIA Long-Life T1000E 8 GB 4mDP Graphics	Y	Y	6V9V4AA/ AT	2	1
	NVIDIA RTX A1000 8 GB 4mDP Graphics	Y	Y	9U276AA	2	1
	NVIDIA RTX™ A2000 6 GB 4mDP Graphics*	Y	Y	340L0AA	2	
	NVIDIA RTX™ A2000 12GB Graphics*	Y	Y	5Z7D9AA/ AT	2	
	NVIDIA RTX 2000 Ada 16 GB 4mDP Graphics	Y	Y	8D6B8AA	2	
	NVIDIA RTX™ A4000 16GB*	Y		20X24AA/ AT	2	
	NVIDIA Long-Life RTX A4000E 16 GB 4DP Graphics*	Y	Y	6H7J7AA	1	
	NVIDIA® RTX™ 4000 Ada 20 GB 4DP Graphics*	Y	Y	8D6B7AA	2	
	NVIDIA <sup>®</sup> RTX™ A4500 20GB GDDR6 4DP Graphics	Y	Y		1	
	NVIDIA Long-Life RTX A2000E 12 GB 4mDP Graphics	Y	Y	6V9V5AA/ AT	2	
	AMD Radeon™ Pro W6600 Graphics (8GB GDDR6 dedicated) *	Y	Y	340K5AA	1	



### HP Z2 G9 Tower Workstation Desktop PC

# QuickSpecs

## **Supported Components**

High-End 3D	AMD Radeon™ Pro W6800 Graphics (32 GB GDDR6 dedicated) *	Y	Y	340K7AA	1
	AMD Radeon Pro W7900 48 GB 3DP+1mDP Graphics	Y	Y	8F699AA	1
	AMD Radeon Pro W7600 8 GB Graphics*	Y		8D6B9AA	1
	AMD Radeon Pro W7500 8 GB Graphics	Y	Y	8D6C2AA	1
	NVIDIA RTX 4500 Ada 24 GB 4DP Graphics	Y	Y	8D6C1AA	1
	NVIDIA® RTX™ A5000 24 GB Graphics*	Y	Y	20X23AA/ AT	1
	NVIDIA RTX 5000 Ada 32 GB 4DP Graphics	Y	Y	8D6B6AA	1
	AMD Radeon™ RX 6700 XT 12GB*	Y	Y	4C203AA	1
	<b>NOTE:</b> Z2 G9 Tower with 700W PSU can sup				

**NOTE:** Z2 G9 Tower with 700W PSU can support up to a 250W professional graphics card from HP, either factory-configured or added via after-market option, and can support up to 320W total graphics power when graphics is factory-configured.

**Note 1:** When dual graphics is configured the 450W and 500W base units will require the AMO HP Z2 TWR Dual Front Fan Kit part number 4N007AA; One storage device configuration for higher than 75W graphics cards (T1000 and up)

\* Requires 700W chassis.

#### Memory

	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP 8GB (1x8GB) DDR5-4800 nECC UDIMM	Y	Y	4M9X9AA	
HP 16GB (1x16GB) DDR5-4800 nECC UDIMM	Y	Y	4M9Y0AA	
HP 16GB (1x16GB) DDR5-4800 ECC UDIMM	Y	Y	4M9Y1AA	1
HP 32GB (1x32GB) DDR5-4800 nECC UDIMM	Y	Y	4M9Y2AA	
HP 32GB (1x32GB) DDR5-4800 ECC UDIMM	Y	Y	4M9Y3AA	1
HP 48GB (1x48GB) DDR5=5600 UDIMM NECC	Y	Y	8F070AA	

#### **NOTE 1:** ECC memory is supported

**GENERAL NOTE:** Two channels of DDR5 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

Though the memory modules can run up to 4800MHz, the current platform will support maximum memory speed of 4400MHz.

The system speed wil Module Configuration	l be determined by a number of key factors: <b>Description of configuration</b>	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system. Memory speed may also vary depending on vendor module mix.	4000MHz
Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB) installed in a system	3600MHz



### **Supported Components**

When more than one memory slot is populated, symmetric configurations are required for 2 DIMMs per channel. Mix of different part numbers or mix of single and dual ranks within a channel is not allowed.

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number
	HP DX175 Removable HDD Frame/Carrier	Ν	Y	1ZX71AA
	HP DX175 Removable HDD Spare Carrier	Ν	Y	1ZX72AA
	HP Z2 TWR SuperMulti DVD-Writer 9.5mm Slim ODD	Y	Y	4L5K0AA
	HP Z2 TWR DVD-ROM 9.5mm Slim ODD	Y	Y	4L5K1AA
	HP CRU QX328 5.25 in Front Removable <u>M.2</u> Frame/Carrier	Y	Y	4N011AA
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD	Y	Y	56Q87AA
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD	Y	Y	56Q88AA
	HP CRU Secure High Performance Storage Module with 512GB M.2 SSD	Y	Y	56Q89AA
	HP CRU SHIPS M.2 Spare Carrier	Y	Y	633X9AA

**NOTES:** Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives. Note that DVD-RAM cannot read or write to 2.6GB Single Sided/5.2 Double Sided-Version 1.0 Media.

4N011AA HP CRU QX328 5.25in Front Removeable Frame/Carrier requires a separate purchase of HP CRU SHIPS Storage Module(s).

HP CRU Secure High Performance Storage (SHIPS) Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier).

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.0)	Y	Ν	
	HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA/AT
	HP Flex 1GbE Fiber LC Single Port	Y	Y	20J15AA
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC <sup>1</sup>	Y	Y	436M8AA
	HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Y	Y	860T8AA
	HP 25GbE SFP28 LC Fiber Optic Transceiver	Y	Y	860T9AA
	Intel Ethernet I350-T4 4-Port 1Gb NIC*	Ν	Y	W8X25AA
	Intel X550 10GBASE-T Dual Port NIC	Y	Y	1QL46AA
	Intel Ethernet Network Adapter I225-T1	Y	Y	406L9AA
	Intel Wi-Fi 6E AX211 BT 5.3 wireless card M.2 non-vPro <sup>1,**,***</sup>	Y	Ν	
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Y	Y	6E3Y9AA/AT
	Intel BE200 Wi-Fi 7 +Bluetooth 5.4 non-vPro WW WLAN**** *Intel I350-T4 4-port GbE NIC is an After Market Option only.	Y		



### Supported Components

<sup>1</sup> Intel AX211 with Internal antenna support WIFI 6/WIFI 6E

\*\*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

\*\*\*Intel AX211 must be configured at time of purchase. Not available as an After Market Option. \*\*\*\* Not available with 12th Gen Intel ADL processors; Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires Windows 11 24H2, select Intel<sup>®</sup> processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backwards compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.

#### NOTES:

The integrated network connection is required to support Intel® vPro® Technology.

If AMT is provisioned, then network teaming with the integrated LAN port is not possible.

"Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.



# **Supported Components**

Input

t Devices	Factory Configured	Option Kit	Option Kit Part Number
HP USB 320K Keyboard	Y	Y	9SR37AA
HP 320M Wired Mouse	Y	Y	9VA80AA
HP Wired Desktop 320MK Mouse and Keyboard	Ν	Y	9SR36AA
HP 125 Wired Keyboard	Y	Y	266C9AA
HP 975 USB+BT Dual Mode Wireless	Ν	Y	3Z726AA
HP 655 Wireless USB BLK KBD/MSE Kit	Ν	Y	N/A
HP 125 Wired Mouse	Y	Y	265A9AA
HP 128 Laser Wired Mouse	Y	Y	265D9AA
HP 935 Creator Wireless Mouse	Ν	Y	1D0K8AA
HP 455 Programmable Wireless Keyboard	Y	Y	4R177AA
HP 455 Programmable Wireless Keyboard (Bulk Qty.12)	Y	Y	4R177A6
HP 655 Wireless Keyboard and Mouse Combo	Y	Y	4R009AA
HP 655 Wireless Keyboard and Mouse Combo (Blk Qty.10)	Y	Y	4R009A6
NOTE: Keyboard and Mouse are optional or add on features	5.		

Flex Module (Rear IO)	Factory Configured	Option Kit	Option Kit Part Number
HP 1GbE LAN Flex Port 2020	Y	Y	141J6AA/AT
HP DP Flex Port 2020	Y	Y	141J7AA/AT
HP Dual USB-A 3.2 Gen1 Flex Port 2020	Y	Y	141J8AA/AT
HP HDMI Flex Port	Y	Y	69D47AA/AT
HP USB-C 3.2 Gen2 Alt Flex Port 2020	Y	Y	141K6AA/AT
HP VGA Flex Port 2020	Y	Y	141K7AA/AT
HP Flex 1GbE Fiber LC Single Port	Y	Υ	20J15AA

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Single TBT3 wType C and USB4 PCIe x4 Card	Y	Ν	N/A
	HP Z2 Internal Serial Port and PS/2 Port	Y	Y	141K9AA/AT
	HP Z2 Power Cord Kit	Y	Y	1N1D5AA
	C13-C14 2.0m 15A 100-127V Countries Straight Desktop Power Cord	Y	Y	8R881AA
	C13-C14 2.0m 10A 200-240V Countries Straight Desktop Power Cord	Y	Y	8R882AA
	HP Z2 2 <sup>nd</sup> serial port adapter	Y	Y	141K8AA/AT
	HP Z2 Tower Dust Filter	Y	Y	141L2AA/AT
	HP Z2 Tower Dust Filter and bezel	Y	Y	141L3AA/AT
	HP PCIe x1 Parallel Port Card	Y	Y	N1M40AA
	HP Z2 G9 Single Type-C SuperSpeed USB 20Gbps Front Port	Y	Y	4M9X8AA/AT
	HP Z2 TWR Dual Front Fan Kit	Y	Y	4N007AA
	HP Optical Bay HDD Mounting Bracket	Y	Y	NQ099AA
	HP Z2 Tower HDD Cable Kit	Ν	Y	6Z9U6AA
	HP Integrated Remote System Controller	Y	Y	7K6D9AA

## HP Z2 G9 Tower Workstation Desktop PC

### **Supported Components**

HP Remote System Controller Main Board Adapter	Y	Y	7K6D8AA
HP Remote System Controller	Y	Y	7K6D7AA
HP Remote System Controller for Universal KVM	Ν	Y	7K7N2AA

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Z2 Mini and Z2/Z4/Z6 TWR Depth Adjustable Fixed Rail Rack Kit	Y	Y	2A8Y5AA
	HP Keyed Cable Lock	Y	Y	T1A62AA
	HP Master Keyed Cable Lock 10mm	Y	Y	T1A63AA
	HP Business PC Security Lock V3 Kit	Y	Y	3XJ17AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Y	Ν	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Y	Ν	2
	HP PC Hardware Diagnostics Windows		Ν	3
	HP Wolf Security	Y	Ν	
	HP Notifications	Y	Ν	
	HP Desktop Support Utility	Y	Ν	
	HP Documentation	Y	Ν	
	HP Image Assistant	Ν	Ν	
	HP Support Assistant	Ν	Ν	
	myHP	Y	Ν	
	HP Easy Clean	Y	Ν	
	Kingsoft WPS Office	Y	Ν	4
	My Office	Y	Ν	5
	Adobe Substance 3D Collection Plan	Ν	Y	6
	WSL2/Ubuntu Data Science Stack	Y	Ν	7
	Wolf Pro Security			8
	Notor			-

**Notes:** 

- 1. Supports, and preinstalled with Windows 10 only. Also available as a free download from http://www.hp.com/go/performanceadvisor
- 2. Windows OS only
- 3. Not available in Russia
- 4. Only available in China
- 5. Only available in Russia
- 6. Not available in China
- 7. Optional Software
- 8. HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish\_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months

### **Supported Components**

after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

#### Operating Systems Windows 11 Pro – HP recommends Windows 11 Pro<sup>2</sup>

Windows 11 Home – HP recommends Windows 11 Pro<sup>2</sup>

Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3

Linux®-ready⁵

Ubuntu<sup>®4,5</sup>

- Intel 12<sup>th</sup> generation processors will support and preinstall Ubuntu 20.02 and 20.04.
- o Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

<sup>1</sup> Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

<sup>2</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

<sup>3</sup>This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

<sup>4</sup> Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

<sup>5</sup>For detailed Linux<sup>®</sup> OS/hardware support information, see: http://www.hp.com/support/linux\_hardware\_matrix

**NOTE:** Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows<sup>®</sup> 8 or Windows 7 operating system on products configured with Intel<sup>®</sup> and AMD<sup>®</sup> 7<sup>th</sup> generation and forward processors or provide any Windows<sup>®</sup> 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



### Supported Components

#### **HP BIOS**

#### Additional HP BIOS Features:

• Power-On password – Helps prevent an unauthorized user from powering on the system.

• Administrator password – Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.

• S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:

-Power to expansion connectors / slots

-Most Wake events other than power buttons and WOL(Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled ) -USB charging ports

#### HP Sure Start Gen7 Start

• BIOS Integrity checking – Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while the system is on.

• Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.

• Protecting beyond BIOS – Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.

• Audit enabled – System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

**NOTE:** HP Sure Start Gen7 is available on HP Workstation products equipped with Intel<sup>®</sup> 12<sup>th</sup> generation processors.

#### **HP Performance Control Modes**

HP Z Desktop Workstations offers Performance Control Modes in the F10 BIOS menu. Z2 G9 offers Quiet Mode, Performance Mode and High-Performance Mode. HP recommends using High Performance Mode unless you have concerns about acoustics in an open office environment. Customers can get up to 41% performance improvements using High Performance Mode over Performance Mode\*. High Performance Mode is configured as default from the factory.

#### How to Set HP Performance Control Modes in HP F10 BIOS Menu

In the F10 BIOS Menu, the setting titled "Performance Control" is adjustable to High Performance Mode, Performance Mode or Quiet Mode. These modes are choice points for performance and acoustic trade-offs based on user needs or recommended balanced conditions in performance and noise optimization.

At startup, push the F10 key while system is booting to get to the BIOS Menu. Go to  $\rightarrow$  Advanced -> System Options ->scroll down and choose "Performance Control"

Set the Performance Mode you desire and then go back to Main->Save Changes and Exit -> Yes The machine will restart in the mode you've chosen.

#### How to change Performance Modes in HP Performance Advisor software?

Select BIOS Settings -> Advanced -> System Options -> Performance Controls

The machine will restart in the mode you've chosen.



## **Supported Components**

You can change these modes anytime you prefer to prioritize acoustics (Quiet Mode), want a balance between performance and acoustics (Performance Mode) or prefer to prioritize performance (High Performance Mode).

For more information on performance control modes, please see the white paper called, HP Performance Control Modes for Z Desktop Workstations.

\*Compared to Performance Mode. Performance improvement based on Z2 Tower G9 with 64GB of memory, 1TB NVMe, Windows 11 22H2 OS, RTX A4000, i7-14700 CPU using Blender OpenData CPU Render and Arnold 2023 CPU multi-core benchmarking.

## SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

#### Software

HP Support Assistant <sup>14</sup> HP Image Assistant HP Desktop Support Utility HP Documentation HP Notifications HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics Windows HP Performance Advisor<sup>1</sup> myHP HP Easy Clean<sup>20</sup> WSL/Ubuntu Data Science Stack HP Privacy Settings Touchpoint Customizer for Commercial

#### **Manageability Features**

HP Driver Packs<sup>2</sup> HP UWP Pack HP System Software Manager (SSM) HP Manageability Integration Kit Gen4<sup>3</sup> HP Smart Support<sup>5</sup> HP Client Catalog (download) HP Image Assistant (download) HP Cloud Recovery HP Client Management Script Library (download) HP BIOSphere Gen6 <sup>13</sup>

#### **Client Security Software**

HP Client Security Suite Gen7<sup>4</sup> including: (including Credential Manager, HP Password Manager<sup>6</sup>, HP Spare Key) HP Power On Authentication Microsoft Defender<sup>7</sup>

#### **Security Management**

HP Secure Erase <sup>16</sup> HP Wolf Pro Security Edition (optional) <sup>18</sup> HP Wolf Security for Business<sup>22</sup> Includes: HP Sure Click<sup>11</sup> HP Sure Sense<sup>12</sup> HP Sure Run Gen5<sup>9</sup> HP Sure Recover Gen4 <sup>10</sup>



### Supported Components

HP Sure Start Gen7<sup>8</sup> HP Tamper Lock HP Sure Admin <sup>17</sup> HP Client Security Manager Gen 7<sup>4</sup>

<sup>1</sup> HP Performance Advisor Software - – P Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor

<sup>2</sup> HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

<sup>3</sup> HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html

<sup>4</sup> HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.

<sup>5</sup> HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

<sup>6</sup> HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

<sup>7</sup> Microsoft Defender Opt in and internet connection required for updates.

<sup>8</sup> HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.

<sup>9</sup> HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel<sup>®</sup> or AMD processors

<sup>10</sup> HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module

<sup>11</sup> HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A\_SureClick for complete details. <sup>12</sup> HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

<sup>13</sup> HP BIOSphere Gen6 features may vary depending on the platform and configurations.

<sup>14</sup> HP Support Assistant requires Windows and Internet access.

<sup>16</sup> Secure Erase – –or the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "C"ear" "anitation method. HP Secure Erase does not support platforms with Intel® Optane.

<sup>17</sup> HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

<sup>18</sup> HP Wolf Pro Security Edition is available preloaded on select SKUs, and, depending on the HP product purchased, includes a license with a term length communicated to you at purchase and in your order confirmation email. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish\_3875769-3873014-16 as that EULA is modified by the following: 7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition is effective upon 4 months after the date the HP Product was shipped by HP and will continue for the term communicated to you at purchase and in your order confirmation email ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support. Notwithstanding the foregoing, the license shall expire no later than one year after the fixed term of the subject license ends.

<sup>20</sup> HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

<sup>22</sup> HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features





**Supported Components** 



# System Technical Specifications

# System Board

System Board Form	
Factor	Customized PCB 36.056 x 25.130 mm (14.197 x 9.894 inch)
Processor Socket	Single LGA-1700
CPU Bus Speed	DMI Gen4
Chipset	Intel® PCH W680
Super I/O Controller	Nuvoton SIO21
<b>Memory Expansion Slots</b>	4 DDR5 memory slots
Memory Type Supported	DDR5, UDIMM (Unbuffered), ECC& non-ECC
Memory Modes	Non-Interleaved for single channel. Interleaved when both channels are populated.
Memory Speed Supported	<b>3</b> 3600MT/s to 4400MT/s DDR5, dependent on memory configuration <sup>1</sup>

<sup>1</sup>Though the memory modules can run up to 4800MHz, the current platform will only be able to support the maximum memory speed of 4400MHz.

	The system speed wil Module Configuration	l be determined by a number of key factors: <b>Description of configuration</b>	Max Memory Speed (Actual Memory speed is dependent on CPU)
	Single DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
	Two single ranked DIMMs in a channel	Configurations with 3 or 4 single ranked DIMMs (8GB and 16GB) installed in a system	4000MHz
	Two dual ranked DIMMs in a channel	Configurations with 3 or 4 dual ranked DIMMs (32GB) installed in a system	3600MHz
Memory Protection	ECC available on data		
Maximum Memory	128GB		
Memory Configuration (Supported)		non-ECC, 16GB and 32GB ECC unbuffered DIMM ot be mixed in the same system	s are supported. ECC and non-ECC
PCI Express Connectors	(1) PCI Expre (1) PCI Expre (1) PCI Expre (1) M.2 2280 (1) M.2 2280 (1) M.2 2280 (1) M.2 2230 NOTE: The P ONLY. HP do May or may 1 512Bytes an	ess Gen5 slot x16 mechanical/x16 electrical (full ress Gen3 slot x4 mechanical/x1 electrical (full ress Gen3 slot x16 mechanical/x4 electrical (full ress Gen3 slot x4 electrical (full ress Gen3 slot x4 electrical (full ress Gen3 slot x4 mechanical/x4 electrical (full ress Gen3 slot x4 electrical (full ress fo	eight, full length, open-ended) height, full length) height, full length, open-ended) -SIG electrical compliance test ards available -in the open market. IS (Maximum Read Request Size) is
Supported Interfaces	SATA	Integrated (4) Serial ATA ir RAID 0 and 1 supported. Fa Microsoft Windows only.	
	Integrated Graphics		n Core i5-12400/i3-12300/i3- UHD Graphics 770 (on 13 <sup>th</sup> and essors);



#### System Technical Specifications Based on Unified Memory Architecture (UMA) - - region of system memory is reserved and dedicated to the graphics displav. Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel<sup>®</sup> UHD Graphics 730/770: Based on Unified Memory Architecture (UMA) - - region of system memory is reserved and dedicated to the graphics display. 2 DP 1.4 graphics ports integrated in motherboard; Supports up to three simultaneous displays across DisplavPort\*/HDMI\*/DVI outputs. Max. resolution supported on onboard DP 1.4/HBR2 ports: 4096x2304 @ 60Hz. 24bpp Max. resolution supported on FlexIO DP 1.4/HBR3 port: 5120x3200 @60Hz, 24bpp **Network Controller** Integrated Ethernet PHY Connection I219LM. Management capabilities: WOL, PXE 2.1 and AMT 16 1 internal header (requires optional Serial Port and PS/2 Serial Combo Kit with PCIe bracket) 2<sup>nd S</sup>erial 1 internal header(requires optional Serial Port Adapter Kit) **USB** Connector(s) 2 Type-A SuperSpeed USB 10Gbps signaling rate port (charge Front supports up to 5V/2.1A): 2 Type-A SuperSpeed USB 10Gbps signaling rate port: 1 Type-C<sup>®</sup> SuperSpeed USB 20Gbps signaling rate port (optional, charge supports up to 5V/3A) Rear 3 High-speed USB 480Mbps signaling rate port; 1 Type-A SuperSpeed USB 5Gbps signaling rate port; 2 Type-A SuperSpeed USB 10Gbps signaling rate port: Flex I/O option: 1 SuperSpeed USB Type-C<sup>®</sup> 10Gbps signaling rate (Power Delivery 15W, Alt Mode DisplayPort); 1 Dual SuperSpeed USB Type-A 5Gbps signaling rate Internal 1 High-speed USB 480Mbps signaling rate header for SD Card Reader **HD Integrated Audio** Realtek ALC3205 Flash ROM Yes **CPU Fan Header** Yes **Memory Fan Header** None **Chassis Fan Header** 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header. **Front PCI Fan Header** None Front Control Panel/Speaker Header Yes CMOS Battery Holder - ithium Yes

hp

Integrated Trusted Platform Module

**Power Supply Headers** 

Power Switch, Power LED & Hard Drive LED Header Yes

**Clear Password Jumper** 

Yes

None

Convertible to FIPS 140-2 Certified mode through firmware v15.21

Integrated TPM 2.0 (Infineon SLB9672)

### System Technical Specifications

#### Keyboard/Mouse

USB or PS/2 (option)

Power Supply 700W EPA92, 500W EPA90, 450W EPA90 and 350W EPA92

<sup>1</sup>Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows<sup>®</sup> 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

<sup>2</sup>M.2 storage supports compatible devices up to 80mm

## PROCESSORS

Name	Ghz P- Core Base Frequenc v	Ghz E- Core Base Frequenc V	Core Max	Up to x GHz E-Core Max Turbo Frequency	L3 Cache (MB)	P- Core S	E- Core S	Total Cores	Processo r Threads	Memory Speed (MT/s) (DDR5) <sup>4</sup>	ECC Memory Supporte d⁵	Integrated Graphics	Featuring Intel® vPro® Technolog y <sup>3</sup>	TDP (W)	Max Turbo Frequen cy (GHz)
Intel 14 <sup>th</sup> Gene	eration Pro		1					1		1					
Intel® Core™ i9-14900K	3.2	2.40	5.6	4.4	36	8	16	24	32	5600	Y	Intel <sup>®</sup> UHD Graphics 770	Y	125	6
Intel® Core™ i9-14900	2	1.50	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.8
Intel® Core™ i7-14700K	3.4	2.50	5.5	4.3	33	8	12	20	28	5600	Y	Intel® UHD Graphics 770	Y	125	5.6
Intel® Core™ i7-14700	2.1	1.50	5.3	4.2	33	8	12	20	28	5600	Y	Intel® UHD Graphics 770	Y	65	5.4
Intel® Core™ i5-14600K	3.5	2.60	5.3	4.2	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.3
Intel® Core™ i5-14600	2.7	2.00	5.2	3.9	24	6	8	14	20	5600	Y	Intel <sup>®</sup> UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-14500	2.6	1.80	5	3.7	24	6	8	14	20	4800	Y	Intel <sup>®</sup> UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-14400	2.5	1.80	4.7	3.5	20	6	4	20	16	4800	N	Intel <sup>®</sup> UHD Graphics 730	N/A	65	4.7
Intel 13 <sup>th</sup> Gene	eration Pro	ocessors										·			
Intel® Core™ i9-13900K	3	2.20	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i9-13900	2	1.50	5.2	4.2	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.6
Intel® Core™ i7-13700K	3.4	2.50	5.3	4.2	30	8	8	16	24	5600	Y	Intel <sup>®</sup> UHD Graphics 770	Y	125	5.8
Intel® Core™ i7-13700	2.1	1.50	5.1	4.10	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-13600K	3.5	2.60	5.1	3.9	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i5-13600	2.7	2.00	5.0	3.7	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-13500	2.5	1.80	4.8	3.5	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-13400	2.5	1.80	4.6	3.3	20	6	4	10	16	4800	N	Intel® UHD Graphics 730	N/A	65	4.6
Intel 12 <sup>th</sup> Gene	eration Pro	ocessors													
Intel® Core™ i9-12900	5	1.8	5.0	3.8	30	8	8	16	24	4800	Y	Intel <sup>®</sup> UHD Graphics 770	Y	65	5.1

(IP)

# System Technical Specifications

Intel® Core™ i7-12700	2.1	1.6	4.8	3.6	25	8	4	12	20	4800	Y	Intel <sup>®</sup> UHD Graphics 770	Y	65	4.9
Intel® Core™ i5-12600	3.3	N/A	4.8	N/A	18	6	0	6	12	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i3-12100	3.3	N/A	4.3	N/A	12	4	0	4	8	4800	N	Intel <sup>®</sup> UHD Graphics 730	N/A	60	4.3
	applicat dependi and/or i <sup>3</sup> Intel T http://v <sup>4</sup> Intel vf enabled order to <sup>5</sup> Memore	ions will ing on ap naming is urbo Boo vww.inte vww.inte vww.inte vro® requ wired L/ o run. Fea ry will run ithin 2DII	necessar plication s not a m st perfor l.com/teo lires Wind AN and/o tures of n at 4400	rily benefi workload easureme mance va chnology/ dows 10 P r Wi-Fi 6E vPro® Ess ) speed (M	t from and yo nt of h ries de turbob ro 64 t WLAN entials T/s) in	use c our h igher pend oost oit or and 2DP(	of this ardw perf ing o for n high CPM 2 Enter C with	s techr are an ormar n hard nore in er, a vl 2.0. So rprise	nology. I Id softwa Ice. Iware, so Iformati Pro supp me func vary. Se IMM pop	Performa are config oftware a on. ported pr tionality e http://i pulation; i	nce and guration and over ocessor require ntel.cor memory	all customers of I clock frequen ns. Intel's numb rall system con s additional 3rd m/vpro v will run at 400 s) in 2DPC with	cy will va bering, br figuratio chipset, ' 'Party sof 00 speed	ry randir n. See vPro tware (MT/s	e in 5) in

# System Technical Specifications

System Configuratio	ns									
Example Configuration	Processor Info	Core i5-12500	D,6C 3.0G 65W							
#1	Memory Info	2 x 8G DDR5 4800 UDIMM NECC								
	Graphics Info	NVIDIA T400 4GB								
	Disks/Optical/Floppy	512GB SSD Z Turbo								
	PSU	350W								
	Other	NA								
Energy Consumption		115	VAC	230 VAC			100 VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows long Idle (SO)	17.	866	17.912		17.804				
	Windows short Idle (SO)	18.	926	19.024		18.	883			
	Windows Busy Typ (SO)	160	.167	155	.973	161	.10			
	Windows Busy Max (SO)	192	.557	187	.067	193	.063			
	Sleep (S3)	1.367	1.259	1.401	1.367	1.259	1.401			
]	Off (S5)	0.555	0.552	0.561	0.555	0.552	0.561			
<u> </u>	Zero Power Mode (EuP)	0.1	71	0.1	73	0.168				

Heat Dissipation		115	VAC	230	VAC	100	VAC			
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows Idle (SO)	60.	959	61.	116	60.	747			
	Windows short Idle (SO)	64.	576	64	.91	64.	429			
	Windows Busy Typ (SO)	546	.489	532	.181	549	.707			
	Windows Busy Max (SO)	657	.003	638	.271	658	.732			
	Sleep (S3)	4.664	4.296	4.78	4.664	4.296	4.78			
	Off (S5)	1.894	1.883	1.914 1.894		1.883	1.914			
	Zero Power Mode (EuP)	0.5	583	0.	59	0.5	573			
Example Configuration	Processor Info	Core i7-12700,12C 2.1G 65W								
#2	Memory Info	2 x 16G DDR5	4800 UDIMM N	NECC						
	Graphics Info	NVIDIA T1000	8GB							
	Disks/Optical/Floppy	512GB SSD Z	Turbo							
	PSU	450W								
	Other	NA								
Energy Consumption		115	VAC	230	VAC	100 VAC				
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows long Idle (SO)	20.	169	20.	335	20.	087			
	Windows short Idle (SO)	21.	222	21.	547	21.	195			
	Windows Busy Typ (SO)	119	9.48	117	.953	120	.406			
	Windows Busy Max (SO)	157	7.13	155	5.03	157	.833			
	Sleep (S3)	1.575	1.461	1.582	1.575	1.461	1.582			
	Off (S5)	0.944	0.941	0.952	0.944	0.941	0.952			
	Zero Power Mode (EuP)	0.2	204	0.2	207	0.2	202			



# System Technical Specifications

Heat Dissipation		115	VAC	230	VAC	100	VAC			
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows Idle (SO)	68.	817	69.	383	68.	537			
	Windows short Idle (SO)	72.	409	73.	518	72.	317			
	Windows Busy Typ (SO)	407	.666	402	.457	410	.824			
	Windows Busy Max (SO)	536	.128	528	.962	538	.527			
	Sleep (S3)	5.374	4.985	5.398	5.374	4.985	5.398			
	Off (S5)	3.221	3.211	3.248 3.221		3.211	3.248			
	Zero Power Mode (EuP)	0.6	596	0.7	706	0.6	589			
Example Configuration	Processor Info	Core i9-12900,16C 2.4G 65W								
#3	Memory Info	2 x 16G DDR5	4800 UDIMM 8	ECC						
	Graphics Info	NVIDIA RTX A	2000							
	Disks/Optical/Floppy	512GB SSD Z	Turbo							
	PSU	450W								
	Other	NA								
Energy Consumption		115	VAC	230	VAC	100 VAC				
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows long Idle (SO)	22.	555	23.	324	22.	484			
	Windows short Idle (SO)	23.	414	24.	656	23.	397			
	Windows Busy Typ (SO)	159	.883	156	.853	161	.463			
	Windows Busy Max (SO)	189	9.99	185	5.89	190.127				
	Sleep (S3)	1.585	1.492	1.694	1.585	1.492	1.694			
	Off (S5)	0.952	0.95	1.083	0.952	0.95	1.083			
	Zero Power Mode (EuP)	0.	21	0.2	217	0.1	98			

Heat Dissipation		115	VAC	230	VAC	100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
				1			
	Windows Idle (SO)	76.9	958	79.	581	76.	715
	Windows short Idle (SO)	79.8	889	84.126		79.831	
	Windows Busy Typ (SO)	545.	.522	535.184		550.913	
	Windows Busy Max (SO)	648.	.246	634.257		648.712	
	Sleep (S3)	5.408	5.091	5.78	5.408	5.091	5.78
	Off (S5)	3.248	3.241	3.695	3.248	3.241	3.695
	Zero Power Mode (EuP)	0.717		0.74		0.676	

**NOTE:** The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2



# System Technical Specifications

Operating Voltage Range	90-269 VAC
Rated Voltage Range	100-240 VAC
<b>Rated Line Frequency</b>	50-60 Hz
Operating Line Frequency Range	47-63 Hz
Rated Input Current	8.2A @ 100-240V
Heat Dissipation	Typical: 1598.101 btu/hr (402.984 kcal/hr) Maximum: 1619.608 btu/hr (408.407 kcal/hr)
ENERGY STAR <sup>®</sup> certified (Config Dependent)	Yes
CECP Compliant @ 220V	Yes
FEMP Standby Power Compliant	Yes, with Wake-on-LAN disabled: <1W in S4/S5 - –ower Off
<b>Built-in Self Test</b> (BIST) <b>LED</b>	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes
Hood Lock Header	Yes
ErP Lot 6- Tier 1 Compliance @ 230V (<1W in S5 - –ower Off)	Yes
ErP Lot 6- Tier 2 Compliance @ 230V (<0.5W in S5 - –ower Off)	Yes

#### Declared Noise Emissions (Entry-level, Mid-level, and High-end configurations; tested on floor)

System Configuration (Mid-level)	Processor Info	Intel® CPU Core i9-12900 16C LGA 2.4 S)	Intel® CPU Core i9-12900 16C LGA 2.40G 30 MB 65W ECC (Intel - –lder Lake- S)		
	Memory Info	4* 32GB 4800 SK hy25ynixemory	4* 32GB 4800 SK hy25ynixemory		
	Graphics Info	NVIDIA® RTX A5000			
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD		
	Power Supply	Chicony 700W EPA92	Chicony 700W EPA92		
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
	Idle	3.59	18.5		
	Hard drive Operating (Drive Random Seek)	3.82	20.1		
	Hard drive Operating (Active mode)	3.97	23.6		
System Configuration	Processor Info	Intel® Core i9-12900K 16C 3.20G LGA 30 MB 125W ECC (Intel - –lder Lake-S)			
(High-end)	Memory Info	4* 32GB 4800 SK hy25ynixemory			
	Graphics Info	NVIDIA <sup>®</sup> RTX A5000			
	Disks/Optical	3*2TB Samsung M.2 SSD; 2*WD 2TB 7	3*2TB Samsung M.2 SSD; 2*WD 2TB 7200RPM SATA HDD		
	Power Supply	Chicony 700W EPA92	Chicony 700W EPA92		



# System Technical Specifications

		Sound Power (LWAd, bels)	<b>Deskside Sound Pressure</b> (LpAm, decibels)
	Idle	3.58	18.2
	Hard drive Operating (Drive Random Seek)	3.78	20
	Hard drive Operating (Active mode)	4.05	20.9

Environmental Requirements	Temperature	Operating: 5° to 35° C (40° to 95° F) Non-operating: -40° to 60° C (-40° to 140° F) Maximum rate of change: 10°C/hr
	Humidity	Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb
	Maximum Altitude	Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet) Non-operating: 12,192 m (40,000 feet) Maximum operating temperature is reduced as altitude increases. See Cooling for details.
	Dynamic	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g
		Vibration
		Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz
	Cooling	Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation, up to 3048 m (10,000 feet)
	NOTE:	System enduring or operating beyond the environmental requirement range is not recommended and may compromise system reliability permanently.



# System Technical Specifications

# **Physical Security and Serviceability**

Access Panel	Tool-less Includes support information
Optical Drive	Tool-less, except for Screw-In carrier
Hard Drives	Tool-less, except for 2.5" "bay
Expansion Cards	Tool-less
Processor Socket	Tool-less, except for the processor heatsink
Blue User Touch Points	Yes, on tool-less internal chassis mechanisms
Color-coordinated Cables and Connectors	Yes
Memory	Tool-less
System Board	Screw-In
Padlock Support	Yes (optional): Locks side cover and secures chassis from theft 0.22-in diameter padlock loop at rear of system
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm slot at rear of system
Universal Chassis Clamp Lock Support	Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable Threaded feature at rear of system
Solenoid Lock and Hood Sensor	Yes (optional) The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The Sensor Kit detects when the access panel has been removed.
Rear Port Control Cover	No
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less
Internal Speaker	Yes
Power Supply Fans	70mm x 70mm x 25mm 4-wire PWM (non-serviceable)
Access Panel Key Lock	No
Integrated Chassis Handles	Rear Recessed Handle
Power Supply	Requires T15 Torx or flat blade screwdriver
PCI Card Retention	Yes, rear (all), middle (optional), front (full-length cards with extender)

## Service, Support, and Warranty

On-site Warranty and Service<sup>1</sup>: Three-years, limited warranty and service offering delivers on-site, next business-day<sup>2</sup> service for parts and labor and includes free telephone support<sup>3</sup> 8am – –pm. Global coverage<sup>2</sup> ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

#### **NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply.

**NOTE 2:** On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

**NOTE 3:** Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at:



## System Technical Specifications

http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

#### **Certification and Compliance**

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)
- •

#### Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex\_r135\_uk/en/any/corp/hpukmu\_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

Please contact techregshelp@hp.com

### BIOS

BIOS 64-bit Services PCI 3.0 Support ATAPI BBS	BIOS supports 64-bit Operating systems only. Full BIOS support for PCI Express through industry standard interfaces. ATAPI Removable Media Device BIOS Specification Version 1.0. BIOS Boot Specification v1.01.(Not support)		
WMI Support	WMI is Microsoft's'implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.		
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.(Not Support)		
BIOS Power On	Users can define a specific date and time for the system to power on.		
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.		
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.		
Replicated Setup	Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).		
SMBIOS	System Management BIOS 3.4, for system management information.		
Boot Control	Disables the ability to boot from removable media on supported devices.		
Memory Change Alert	Alerts management console if memory is removed or changed.		
Thermal Alert	Monitors the temperature state within the chassis. Three modes:		
	• NORMAL - –ormal temperature ranges.		
	• ALERTED – –xcessive temperatures are detected. Raises a flag so action can be taken to avoid		



# System Technical Specifications

	shutdown or provide for a smoother system shutdown. • SHUTDOWN - –xcessive temperatures are encountered. Automatically shuts down the computer without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced	Allows the system to enter and resume from low power modes (sleep states).
Configuration and Power Management Interface)	Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
<b>A 11 T</b>	Supports ACPI 6.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - –CPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System	Allows a new or existing system to boot over the network and download software, including the
Installation via F12 (PXE	operating system.
2.1) (Remote Boot from Server)	
Server) ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is
	available through an industry standard interface (SMBIOS and WMI) so that management SW applications can use and report this information.
System board revision	Allows management SW to read revision level of the system board.
level	Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
	Contains an team that is detected addition of a set is and same
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
-	
hardware installed	
hardware installed Keyboard-less Operation	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with
hardware installed Keyboard-less Operation Localized ROM Setup	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED.
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE)	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI PCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI PCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 3.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 2.0 PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0(Not support) PCI Express Base Specification, Revision 3.0
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI PCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 1.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 3.0
hardware installed Keyboard-less Operation Localized ROM Setup Asset Tag Per-slot Control Adaptive Cooling Pre-boot Diagnostics UEFI Specification Revision ACPI ATA (IDE) CD Boot EDD EHCI PCI	The system can be booted without a keyboard. Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with local keyboard mappings. The user or MIS to set a unique tag string in non-volatile memory. Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED. 2.7 Advanced Configuration and Power Management Interface, Version 6.0 AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b "E" Torito" "ootable CD-ROM Format Specification Version 1.0 Enhanced Disk Drive Specification Version 3.1 BIOS Enhanced Disk Drive Specification Version 3.0(Not support) Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0 PCI Local Bus Specification, Revision 2.3 PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 2.0 PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0(Not support) PCI Express Base Specification, Revision 3.0



### System Technical Specifications

SATA	Serial ATA Specification, Revision 1.0a Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0
SPD	JEDEC JESD300-5
ТРМ	Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670). Common Criteria EAL4+ certified. FIPS 140-2 Certification
	TCG TPM Certified products list:
	http://www.trustedcomputinggroup.org/certification/tpm-certified-products/
UHCI	Universal Host Controller Interface Design Guide, Revision 1.1
USB	Universal Serial Bus Revision 1.1 Specification
	Universal Serial Bus Revision 2.0 Specification
	Universal Serial Bus Revision 3.1 Specification
	Universal Serial Bus Revision 3.2 Specification
SMBIOS	System Management BIOS Reference Specification, Version 3.4
	External BIOS simulator found at: http://csrsml.itcs.hp.com/

# Social and Environmental Responsibility

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
System Configuration	The configuration used for the Ene Notebook model is based on a "Typ	rgy Consumption and Declared Noise ically Configured Notebook".	e Emissions data for the
Sustainable Impact Specifications	<ul> <li>Japan PC Green label*</li> <li>Product Carbon Footprint (</li> <li>Ocean-bound plastic in Systems 50% post-consumer recycles)</li> <li>Low halogen</li> <li>Outside Box and corrugated</li> </ul>	stem FAN, CPU FAN and Speaker	-
	<ul> <li>labeled with one or more of these r</li> <li>IT ECO declaration</li> <li>US ENERGY STAR<sup>®</sup></li> <li>US Federal Energy Manage</li> <li>EPEAT<sup>®</sup> Gold with Climate levels by country</li> <li>TCO Certified</li> <li>China Energy Conservation</li> <li>China State Environmenta</li> <li>Taiwan Green Mark</li> </ul>	ement Program (FEMP) + registered. See www.epeat.net for	
Eco-Label Certifications & Declarations	CRU QX 428 & QX448 removable st Broadcom 5720-2P NIC Card, powe purchase may not be Low Halogen.		enol 10 & 25 Gb Transceivers, vice parts obtained after



# System Technical Specifications

Normal Operation (Sort idle)	34.16 W	34.01 W	34.39 W
Normal Operation (Long idle)	32.77 W	32.74 W	33.15 W
Sleep	2.57 W	2.54 W	2.57 W
Off	0.67 W	0.68 W	0.67 W

#### NOTE:

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Energy efficiency data listed is for an ENERGY STAR<sup>®</sup> compliant product if offered within the model family . HP computers marked with the ENERGY STAR<sup>®</sup> Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR<sup>®</sup> specifications for computers. If a model family does not offer ENERGY STAR<sup>®</sup> compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows<sup>®</sup> operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	116.8 BTU/hr	116.3 BTU/hr	117.6 BTU/hr
Normal Operation (Long idle)	112.1 BTU/hr	112 BTU/hr	113.4 BTU/hr
Sleep	8.8 BTU/hr	8.7 BTU/hr	8.8 BTU/hr
Off	2.3 BTU/hr	2.3 BTU/hr	2.3 BTU/hr
*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is			uming the service level is

# **\*NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- 2011/65/EC.
  This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
  - This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).

This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -

- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.8% recycle-able when properly disposed of at end of life.

Packaging Materials	External:	PAPER/Corrugated	1214 g
		PAPER/Molded Pulp	890 g
	Internal:	PLASTIC/Polyethylene low density - DPE	– 40 g
	The plastic packaging material contains at least 0.0% recycled content.		
	The corrugated paper packaging materials contains at least 62.5% recycled content.		cled content.
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to ou products worldwide through the HP GSE. HP has contributed to the development of related legislat Europe, as well as China, India, and Vietnam.		nces (RoHS) Directive to our



# System Technical Specifications

	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances— including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.
	We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.
	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):
	<ul> <li>Asbestos</li> <li>Certain Azo Colorants</li> <li>Certain Brominated Flame Retardants – may not be used as flame retardants in plastics</li> <li>Cadmium</li> <li>Chlorinated Hydrocarbons</li> <li>Chlorinated Paraffins</li> <li>Bis(2-Ethylhexyl) phthalate (DEHP)</li> <li>Benzyl butyl phthalate (DBP)</li> <li>Dibutyl phthalate (DBP)</li> <li>Dibutyl phthalate (DBP)</li> <li>Diboutyl phthalate (DIBP)</li> <li>Formaldehyde</li> <li>Halogenated Diphenyl Methanes</li> <li>Lead carbonates and sulfates</li> <li>Lead and Lead compounds</li> <li>Mercuric Oxide Batteries</li> <li>Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.</li> <li>Ozone Depleting Substances</li> <li>Polybrominated Biphenyl CPBBs)</li> <li>Polybrominated Biphenyl Oxides (PBBOs)</li> <li>Polychlorinated Biphenyl (PCB)</li> <li>Polychlorinated Terphenyls (PCT)</li> <li>Polyulyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.</li> <li>Radioactive Substances</li> <li>Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)</li> </ul>
Packaging Usage	<ul> <li>HP follows these guidelines to decrease the environmental impact of product packaging:</li> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging</li> </ul>
	<ul> <li>materials.</li> <li>Eliminate the use of ozone-depleting substances (ODS) in packaging materials.</li> <li>Design packaging materials for ease of disassembly.</li> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> </ul>



# System Technical Specifications

• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <a href="http://www.hp.com/go/reuse-recycle">http://www.hp.com/go/reuse-recycle</a> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: <a href="http://www.hp.com/go/recyclers">http://www.hp.com/go/recyclers</a> . These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Information	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
footnotes	<ul> <li>Percentage of ocean-bound plastic contained in each component varies by product</li> </ul>
	<ul> <li>Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.</li> </ul>
	• External power supplies, WWAN modules, power cords, cables and peripherals excluded.
	• 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
	<ul> <li>Fiber cushions made from 100% recycled wood fiber and organic materials.</li> </ul>



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### **Technical Specifications - Hard Drives**

SATA Hard Drives for HP Workstations	500GB SATA 7200 rpm 6Gb/s 3.5" "DD	Capacity	500GB	
		Protocol	SATA	
"		Controller	AHCI	
		Height	1 in; 2.54 cm	
		Width	Media Diameter	3.5 in; 8.9 cm
			Physical Size	4 in; 10.17 cm
		Interface	Serial ATA (6.0Gb/s), NCQ enabled	
		<b>Synchronous Transfer</b> Rate (Maximum)	Up to 600MB/s *	
		Buffer	32MB	
		<b>Seek Time</b> (typical reads, includes controller overhead, including settling)	Single Track	2 ms *
			Average	11 ms *
			Full Stroke	21 ms *
		<b>Rotational Speed</b>	7,200 rpm	
		Logical Blocks	976,773,168	
		Operating Temperature	41° to 131° F (5° to 55	° C)
	-	Vary. 3 = 1 billion bytes. TB = 1 trillior s reserved for system recovery	-	apacity is less. Up to 36GB of

1TB SATA 7200 rpm	Capacity	1TB	
6Gb/s 3.5" "DD	Protocol	SATA	
	Controller	AHCI	
	Height	1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0Gb/s), NCQ enabled	
	<b>Synchronous Transfer</b> Rate (Maximum)	Up to 600 MB/s *	
	Buffer	64MB	
	<b>Seek Time</b> (typical reads, includes controller overhead, including settling)	Single Track	2 ms *
		Average	11 ms *
		Full Stroke	21 ms *
	Rotational Speed	7,200 rpm	
	Logical Blocks	1,953,525,168	
	Operating Temperature	41° to 131° F (5° to 55°	C)
*Actual performance may	varv		

\*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" "DD	Capacity	2TB	
	Protocol	SATA	
	Controller	AHCI	
	Annualized Failure Rate (based on Rated POH)	<0.62%	
	Height	1 in; 2.54 cm	
	Width	Media Diameter	3.5 in; 8.9 cm



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## **Technical Specifications - Hard Drives**

	Physical Size	4 in; 10.17 cm
Interface	Serial ATA (6.0 Gb/s), NCQ Enabled	
Synchronous Transfer Rate (Maximum)	Up to 600MB/s *	
Buffer	64MB	
Seek Time (typical reads, includes controller overhead, including settling)	Single Track	2.0 ms *
	Average	11 ms *
	Full Stroke	21 ms *
Rotational Speed	7,200 rpm	
Logical Blocks	3,907,029,168	
Operating Temperature	41° to 131° F (5° to 55° C)	

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200 rpm 6Gb/s 3.5" "DD	Capacity	1TB	
	Height	1 in; 2.54 cm	
(Enterprise Class)	Protocol	SATA	
	Controller	AHCI	
	Reliability	2.0M hours	
	<b>Rated Power On Hours</b>	8760/yr	
	Annualized Failure Rate (based on Rated POH)	<0.62%	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6.0 Gb/s), NCQ Enabled	
	<b>Synchronous Transfer</b> <b>Rate</b> (Maximum)	Up to 600MB/s *	
	Buffer	128MB	
	Seek Time (typical reads,	Single Track	0.32ms*
	includes controller overhead, including settling)	Average	7.45ms*
		Full Stroke	14.2ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	41° to 140° F (5° to 60° C)	
	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*
	<b>Enterprise Class Features</b>	High Reliability	

#### \*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" "DD (Enterprise Class)	Capacity	2TB
	Protocol	SATA
	Controller	AHCI
	Reliability (MTBF)	2.0M hours
	<b>Rated Power On Hours</b>	8760/yr



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## **Technical Specifications - Hard Drives**

Annualized Failure Rate (based on Rated POH)	<0.62%	
Rated for 24/7/365 Operation		
Physical Size (Height)	1 in; 2.54 cm	
Physical Size (Width)	4 in; 10.17 cm	
Media Diameter	3.5 in; 8.9 cm	
Interface	Serial ATA (6Gb/s), NCQ	enabled
Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
Buffer	128MB	
Seek Time (typical reads,	Single Track	0.7ms*
includes controller	Average	8.5ms*
overhead, including settling)	Full Stroke	15.7ms*
<b>Rotational Speed</b>	7,200 rpm	
Operating Temperature	41° to 131° F (5° to 55° (	<u>-</u> )
Performance	Sequential Read	up to 226MB/s*
	Sequential Write	up to 226MB/s*
	Diale Dallah Iling	

Enterprise Class Features High Reliability

#### \*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB SATA 7200 rpm 6Gb/s 3.5" "DD	Capacity	4TB	
	Protocol	SATA	
(Enterprise Class)	Controller	AHCI	
	Reliability	2.0M hours	
	<b>Rated Power On Hours</b>	8760/yr	
	<b>Annualized Failure Rate</b> (based on Rated POH)	<0.62%	
	Rated for 24/7/365 Operation		
	Physical Size (Height)	1 in; 2.54 cm	
	Physical Size (Width)	4 in; 10.17 cm	
	Media Diameter	3.5 in; 8.9 cm	
	Physical Size	4 in; 10.17 cm	
	Interface	Serial ATA (6Gb/s), NCQ	enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
	Buffer	256MB	
	Seek Time (typical reads,	Single Track	0.7ms*
	includes controller	Average	8.5ms*
	overhead, including settling)	Full Stroke	15.7ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	41° to 131° F (5° to 55° C)	



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	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*
	<b>Enterprise Class Features</b>	•	•
*Actual performance may v <b>NOTE:</b> For storage drives, GB system disk (for Windows) is r	vary.	bytes. Actual formattee	l capacity is less. Up to 36GB of
8TB SATA 7200 rpm 6Gb/s	s Capacity	8TB	
3.5" "DD (Enterprise	Protocol	SATA	
Class)	Controller	AHCI	
	Reliability	2.0M hours	
	Width	Media Diameter	3.5 in; 8.9 cm
		Physical Size	4 in; 10.17 cm
	Interface	Serial ATA (6Gb/s),	NCQ enabled
	<b>Synchronous Transfer</b> Rate (Maximum)	Up to 600MB/s*	
	Buffer	256MB	
	Seek Time (typical reads,	Single Track	0.7ms*
	includes controller overhead, including	Average	8.5ms*
	settling)	Full Stroke	15.7ms*
	Rotational Speed	7,200 rpm	
	Operating Temperature	41° to 140° F (5° to	60° C)
	Performance	Sequential Read	up to 226MB/s*
		Sequential Write	up to 226MB/s*
	Enterprise Class Features	s High Reliability	
			d capacity is less. Up to 36GB of
500GB SATA 7.2K SED	Capacity	500GB	
2.5" "DD	Protocol	SATA	
	Height	0.275 in; 0.7 cm	
	Width	Media Diameter	2.5 in; 6.36 cm
		Physical Size	2.75 in; 6.99 cm
	Interface	Serial ATA (6.0Gb/s)	, NCQ enabled
	Synchronous Transfer Rate (Maximum)	Up to 600MB/s*	
	Buffer	64MB	
	Seek Time (typical reads,	Single Track	1ms*
	includes controller overhead, including	Average	4.2ms*
	settling)	Full Stroke	25ms (Typical)*
	Rotational Speed	7,200 rpm	
	Operating Temperature	32° to 131° F (0° to 6	50° C)
	Self-Encrypting Drive	Yes	

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\*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 512GB TLC PCIe SSD (Z2G9)	Capacity	512GB	
	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	150TBW (TB Written)	
	Reliability (MTBF)	1.5M hours	
	Interface	PCI Express 4.0 x4 electrical	
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6400MB/s*
		Sequential Write	3400MB/s*
		Random Read	600K IOPS*
		Random Write	600K IOPS*

#### \*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4	Capacity	1TB	
1TB TLC PCIe SSD (Z2G9)	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	trical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*

\*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4	Capacity	2ТВ
2TB TLC PCIe SSD (Z2G9)	Protocol	PCIe
	Form Factor	M.2 in native Slot on motherboard
	Controller	NVMe
	NAND Type	3D TLC
	Endurance	500TBW (TB Written)
	Reliability	1.5M Hours
	Interface	PCI Express 4.0 x4 electrical



	Operating Temperature	22º to 170º E (0º to 01º	C)
	Operating Temperature Performance		
	Periormance	Sequential Read	6500MB/s*
		Sequential Write Random Read	5000MB/s*
		Random Keaŭ Random Write	800K IOPS*
*		Random write	800K IOPS*
	vary. = 1 billion bytes. TB = 1 trillior is reserved for system recove		pacity is less. Up to 36GB
HP Z Turbo Drv PCIE-4X4	Capacity	4TB	
4TB	Protocol	PCIe	
TLC PCIe SSD	Form Factor	M.2 in native Slot on m	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	600TBW (TB Written)	
	Reliability (MTBF)	1.5M Hours	
	Interface	PCI Express 4.0 x4 elec	trical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	700K IOPS*
		Random Write	700K IOPS*
	vary. GB = 1 billion bytes. TB = 1 t : (for Windows) is reserved f		
HP Z Turbo Drv PCIE	Capacity	4TB	
Gen4x4 4TB	Protocol	PCIe	
TLC PCIe SED OPAL2	Form Factor	M.2 in native Slot on m	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	600TBW (TB Written)	
	Interface	PCI Express 4.0 x4 elec	trical
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	700K IOPS*
		Random Write	700K IOPS*
	Self-Encrypting Drive	OPAL2	

#### Self-Encrypting Drive Support

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 512GB	Capacity	512GB
	Protocol	PCle



**TLC PCIe SED** OPAL2 (Z2G9)

Form Factor	M.2 in native Slot on motherboard	
Controller	NVMe	
NAND Type	3D TLC	
Endurance	150TBW (TB Written)	
Reliability	1.5M Hours	
Interface	PCI Express 4.0 x4 electrical	
<b>Operating Temperature</b>	32° to 178° F (0° to 81° C)	
Performance	Sequential Read 6400MB/s*	
	Sequential Write	3400MB/s*
	Random Read	600K IOPS*
	Random Write	600K IOPS*
Self-Encrypting Drive	OPAL2	

Support

#### \*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 1TB	Capacity	1TB	
TLC PCIe SED	Protocol	PCIe	
OPAL2 (Z2G9)	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 electrical	
	Operating Temperature	32° to 178° F (0° to 81°	C)
	Performance	Sequential Read	6500MB/s*
		Sequential Write	5000MB/s*
		Random Read	800K IOPS*
		Random Write	800K IOPS*
	Self-Encrypting Drive	OPAL2	

Support

\*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 2TB	Capacity	2TB	
TLC PCIe SED OPAL2 (Z2G9)	Protocol	PCIe	
	Form Factor	M.2 in native Slot on motherboard	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	500TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 electrical	
	Operating Temperature	re 32° to 178° F (0° to 81° C)	
	Performance	Sequential Read	6500MB/s*



Sequential Write	5000MB/s*
Random Read	800K IOPS*
Random Write	800K IOPS*
OPAL2	

#### Self-Encrypting Drive Support

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB 2280 PCIe-4x4	Capacity	256GB	
Value M.2 SSD	Protocol	PCle	
	Form Factor	M.2 in native Slot on motherboard	
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	150TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elec	trical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3100MB/s*
		Sequential Write	1400MB/s*
		Random Read	200K IOPS*
		Random Write	400K I0PS*

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

512GB 2280 PCIe-4x4	Capacity	512GB	
Value M.2 SSD	Protocol	PCIe	
	Form Factor	M.2 in native Slot on mo	otherboard
	Controller	NVMe	
	NAND Type	3D TLC	
	Endurance	300TBW (TB Written)	
	Reliability	1.5M Hours	
	Interface	PCI Express 4.0 x4 elect	rical
	Operating Temperature	32° to 158° F (0° to 70°	C)
	Performance	Sequential Read	3400MB/s*
		Sequential Write	2500MB/s*
		Random Read	380K IOPS*
		Random Write	430K IOPS*

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB 2280 PCIe-4x4 Value	Capacity	1TB
M.2 SSD	Protocol	PCIe
	Form Factor	M.2 in native Slot on motherboard
	Controller	NVMe



NAND Type	3D TLC	
Endurance	400TBW (TB Written)	
Reliability	1.5M Hours	
Interface	PCI Express 4.0 x4 electrical	
Operating Temperature	32° to 158° F (0° to 70° C)	
Performance	Sequential Read 3400MB/s*	
	Sequential Write	2500MB/s*
	Random Read	500K IOPS*
	Random Write	440K IOPS*

\*Actual performance may vary.

**NOTE:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



# QuickSpecs

AMD Radeon™ Pro	Form Factor	Single slot, full-height, 9.5" length
	Graphics Controller	Navi23 architecture
•	or apines controtter	Power: 122 Watts
		Cooling Solution: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x8
	Memory	8GB GDDR6 Memory
		Memory Bandwidth: 224 GB/s
	Commontowe	Memory Interface: 128 bit
	Connectors	4x DisplayPort™ 1.4 with DSC - HDR Ready
		- Supports Multi-Stream Transport (MST)
	Max simultaneous	@ 60Hz with HDR Enabled
	displays	4x @ 3840x2160px (4K)
		4x @ 5120x2880px (5K)
	Chading Architecture	1x @ 7680x4320px (8K) DirectX 12 Shader Model 6.5
	Shading Architecture	DirectX <sup>®</sup> 12 Ultimate
	Supported Graphics APIs	OpenGL <sup>®</sup> 4.6
		OpenCL™ 2.1
		Vulkan™ 1.2
	Available Graphics	Windows 10 64-bit
	Drivers	Windows 11 64-bit
		Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support
		Web site:
		http://welcome.hp.com/country/us/en/support.html
AMD Radeon™ Pro W6800	Form Factor	Double slot, full-height, 10.5" length
32GB Graphics	Graphics Controller	Navi21 architecture
	diapines controller	Power: 261 Watts
		Cooling Solution: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	8GB GDDR6 Memory
		Memory Bandwidth: 512 GB/s Memory Interface: 256 bit
	Connectors	-
	Connectors	6x Mini-DisplayPort™ 1.4 with DSC - HDR Ready
		- Supports Multi-Stream Transport (MST)
	Max simultaneous	@ 60Hz with HDR Enabled
	displays	6x @ 3840x2160px (4K)
		6x @ 5120x2880px (5K)
	Chading Architacture	2x @ 7680x4320px (8K) DirectX 12 Shader Madel 6 5
	Shading Architecture	DirectX 12 Shader Model 6.5
	Supported Graphics APIs	DirectX®12 Ultimate OpenGL® 4.6
		OpenCL <sup>™</sup> 2.1
		Vulkan™ 1.2



(III)

NVIDIA® T400 4GB	Form Factor	Single Slot, Low Profile (2.7" H x 6.1" L)
Graphics	Graphics Controller	Turing architecture Max Power: 30 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	4GB GDDR6 Memory Memory Bandwidth: 80 GB/s Memory Interface: 64 bit
	Connectors	3x mDP (Mini DisplayPort™ ) 1.4 Connectors
	Max simultaneous displays	- 3x 3840 x 2160 @ 120Hz - 3x 5120 x 2880 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® T600 4GB	Form Factor	Single Slot, Low Profile (2.7" H x 6.1" L)
Graphics*	Graphics Controller	Turing architecture Max Power: 40 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	4GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)



HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html

#### AMD<sup>®</sup> Radeon<sup>™</sup> RX 6400 Form Factor Single slot, Low Profile (2.8" H x **4GB** Graphics 6.3"L) Weight: 155g Radeon<sup>™</sup> RX 6400 **Graphics Controller** Max Power: 53W Cooling Solution: Active axial fan Architecture: RDNA<sup>™</sup> 2 **Bus Type** PCI Express x4 Gen4 Size: 4GB GDDR6 Memory Interface: 64-bit Bandwidth: up to 128 GB/s DP (DisplayPort<sup>™</sup>) 1.4 + HDMI 2.1 Connectors Max simultaneous - up to 4x 5120 x 2880 x 24 bpp @ displays 60Hz **Shading Architecture** Microsoft DirectX 12 Shader Model 5.1 OpenGL<sup>®</sup> 4.6 Supported Graphics APIs DirectX<sup>®</sup> 12 Ultimate Vulkan™ 1.1 API support includes: OpenCL<sup>™</sup> 2.2 Microsoft Windows 10 64-bit, Windows 11 64-bit **Available Graphics** Drivers HP qualified drivers may be preloaded or the latest prosumer graphics drivers are available from the AMD.com Notes This is a Prosumer or Consumer graphics card, and not a Professional graphics card. As such, it does not have formal professional application validation, but is intended per AMD to function properly for game development, real-time engine, and many prosumer application workloads. Customers using Prosumer or Consumer graphic cards with axial fan cooling solutions are likely to experience higher acoustics in comparison with Professional graphic cards that use blower fan cooling. NVIDIA® T1000 4GB Single Slot, Low Profile (2.7" H x **Form Factor** Graphics 6.1" L) **Graphics Controller Turing architecture** Max Power: 50 Watts **Cooling Solution: Active fan heatsink** PCI Express 3.0 x16 **Bus Type** Memory 4GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit Connectors 4x mDP (Mini DisplayPort<sup>™</sup>) 1.4 Connectors

#### \*May go End of Life in late 2022



	Max simultaneous displays Shading Architecture Supported Graphics APIs	<ul> <li>4x 3840 x 2160 @ 120Hz</li> <li>4x 5120 x 2880 @ 60Hz</li> <li>2x 7680 x 4320 @ 60Hz</li> <li>supports Multi-Stream Transport (MST)</li> <li>DirectX 12 Shader Model 5.1</li> <li>OpenGL 4.6</li> <li>DirectX 12</li> <li>Vulkan 1.2</li> <li>API support includes:</li> <li>CUDA, OpenCL 1.2</li> </ul>
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® T1000 8GB Graphics	Form Factor	Single Slot, Low Profile (2.7" H x 6.1" L)
	Graphics Controller	Turing architecture Max Power: 50 Watts Cooling Solution: Active fan heatsink
	Bus Type	PCI Express 3.0 x16
	Memory	8GB GDDR6 Memory Memory Bandwidth: 160 GB/s Memory Interface: 128 bit
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz - supports Multi-Stream Transport (MST)
	Shading Architecture	DirectX 12 Shader Model 5.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX 2000 Ada	Form Factor	Half Height Dual Slot (2.7" Height x 6.7" Length)
	Max Power Consumption	70W



# QuickSpecs

	GPU Memory	16GB GDDR6 Memory Bandwidth: 224 GB/s Memory Width: 128-bit
	Connectors	4x Mini DisplayPort 1.4a
	Maximum Resolution	4x 4096 x 2160 @ 120 Hz 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	Bus Type	PCI Exress 4.0 x8
	Avaliable Drivers	Windows 10 Windows 11
NVIDIA® RTX™ A2000 12GB Graphics	Form Factor	Low-Profile Double Slot (2.7" H x 6.1" L)
	Graphics Controller	Ampere architecture Power: 70 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	12GB GDDR6 memory Memory Bandwidth: 288 GB/s Memory Interface: 192 bit Support Error-correcting code (ECC)
	Connectors	4x mDP (Mini DisplayPort™) 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX 4000 Ada	Form Factor	Full-Height Triple Slot (4.4" Height x 11.5" Length)
	Max Power Consumption	130W
	GPU Memory	20GB GDDR6 Memory Bandwidth: 360 GB/s Memory Width: 160-bit
	Connectors	4x DisplayPort 1.4a Requires: 1x 16-pin CEM 5 power connector (adapter may be needed)



# QuickSpecs

	Bus Type	PCI Exress 4.0 x16
	Avaliable Drivers	Windows 10 Windows 11
NVIDIA® RTX™ A4000 I6GB Graphics	Form Factor	Full Height Single Slot (9.5" Length)
	Graphics Controller	Ampere architecture Power: 140 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	16GB GDDR6 memory Memory Bandwidth: 448 GB/s Memory Interface: 256 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX™ A4500 20GB Graphics	Form Factor	Full Height Double Slot (10.5" Length)
	Graphics Controller	Ampere architecture Power: 200 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	20GB GDDR6 memory Memory Bandwidth: 640 GB/s Memory Interface: 320 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2



	Available Graphics Drivers	API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions) HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
NVIDIA® RTX™ A5000 24GB Graphics	Form Factor	Full Height Double Slot (10.5" Length)
	Graphics Controller	Ampere architecture Power: 230 Watts Cooling: Active Fan Heatsink
	Bus Type	PCI Express 4.0 x16
	Memory	24GB GDDR6 memory Memory Bandwidth: 768 GB/s Memory Interface: 384 bit Support Error-correcting code (ECC)
	Connectors	4x DP 1.4 Connectors
	Max simultaneous displays	4x 4096 x 2160 @ 120 Hz, 4x 5120 x 2880 @ 60 Hz, 2x 7680 x 4320 @ 60 Hz
	Shading Architecture	Shader Model 6.5
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Vulkan 1.2 API support includes: CUDA, OpenCL 1.2
	Available Graphics Drivers	Windows 10 64-bit Windows 11 64-bit Linux® 64-bit (selected Enterprise distributions)
		HP qualified drivers may be preloaded or available from the HP support Web site: http://welcome.hp.com/country/us/en/support.html
AMD® Radeon™ Pro W7600 8GB	Form Factor	Full-Height Single Slot (4.38" "eight x 9.5" "ength)
	Max Power Consumption	130W
	GPU Memory	8GB GDDR6 Memory Bandwidth: 288 GB/s Memory Width: 128-bit
	Connectors	4x DP 2.1 Requires : 1x 6-pin PCIe Aux Power
	Maximum Resolution	4x @ 3840x2160 (4K) 4x @ 5120x2880 (5K) 2x @ 7680x4320 (8K)
	Bus Type	PCI Express 4.0 x8



# QuickSpecs

### **Technical Specifications - Graphics**

	Available Graphics Drivers	Windows 10 Windows 11
MD <sup>®</sup> Radeon™	Form Factor	<del>Full-Height Single S</del> lot (4.38" "eight x 8.5" "ength)
Pro W7500 8GB	Max Power Consumption	70W
	GPU Memory	8 GB GDDR6 Memory Bandwidth: 173 GB/s Memory Width: 128-bit
	Connectors	4x DP 2.1
	Maximum Resolution	4x @ 3840x2160 (4K) 4x @ 5120x2880 (5K) 2x @ 7680x4320 (8K)
	Bus Type	PCI Express 4.0 x8
	Available Graphics Drivers	Windows 10 Windows 11
AMD Radeon™ RX 6700 XT	Form Factor	Dual slot, Full Length (254mm L x 38mm W x 108.65mm H)
	Graphics Controller	AMD Radeon™ RX 6700 XT Graphics GPU: 2560 Navi2 Stream Processors Memory: 12GB GDDR6 Power: 230 Watts, Standard graphics 8pin + 6pin auxiliary power Cooling: Active, Dual Axial fan
	Bus Type	PCI Express 4.0 x16
	Connectors	3DP 1.4 + HDMI 2.1 Outputs
	Maximum Resolution	DisplayPort™ 1.4 with DSC: - up to 4x 5210 x 3200 x 24 bpp @ 60Hz, uncompressed - up to 7680 x 4320, compressed Display Outputs 3 DP + 1 HMDI
	Shading Architecture	Microsoft DirectX 12 Shader Model 6.1
	Supported Graphics APIs	OpenGL 4.6 DirectX 12 Feature Level 12_1 Vulkan 1.1 OpenCL 2.2
	Available Graphics Drivers	Windows 11 Linux® 64-bit (selected distributions) Typically, latest drivers will be available from amd.com
	does not have formal prof for game development, re Prosumer or Consumer gra Professional graphic cards	or Consumer graphics card, and not a Professional graphics card. As such, it essional application validation, but is intended per AMD to function properly al-time engine, and many prosumer application workloads. Customers using aphic cards are likely to experience higher acoustics in comparison with b. The higher acoustics observed with non-professional graphics is expected, ns do not have control in this area.
HP 9.5mm Slim DVD	Description	9.5mm height, tray-load
Writer	<b>Mounting Orientation</b>	Either horizontal or vertical
	Interface Type	SATA/ATAPI
	Dimensions (WxHxD)	128 x 9.5 x 127mm
	Supported Media Types	DVD+R



DVD+RW

commercially avail storage of your origingle layer discs. H	able DVD movies or other copyrig ginal material and other lawful us	RAM (DVD Writer). Does not permit copying of ht protected materials. Intended for creation and ses. Double Layer discs can store more data than ed with this drive may not be compatible with		
		nel I/O Connectivity Design Guide V. 1.3, FCC, CE, UL, TUVT		
Approvals	USB-IF, WHQL, Complian Specification Rev. 1.0,	USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0.		
Kit Contents	HP SATA DVD Writer driv	-		
Operating Systems Supported		Windows 11, Windows 10, Windows 7 Professional 64-bit, Windows Vista Business 64*, Windows 2000. Linux®.		
	Temperature			
condensing)	Relative Humidity Maximum Wet Bulb	10% to 80% 84° F (29° C)		
(all conditions non-	mental Temperature			
Aporating Environ		5 VDC -< 800 mA typical, <1600 mA maximu 41° to 122° F (5° to 50° C)		
	DC Power Requirements DC Current			
Power	Source	SATA DC power receptacle		
		DVD-R Up to 8X		
		DVD+R Up to 8X		
		DVD-ROM DL Up to 8X		
		DVD-R DL Up to 8X DVD-ROM Up to 8X		
		DVD+R DL Up to 8X		
		DVD-RW Up to 8X		
	DVD ROM Read	DVD+RW Up to 8X		
Rates		CD-RW Up to 24X		
Maximum Data Tra	ansfer CD ROM Read	CD-ROM, CD-R Up to 24X		
	Full Stroke CD	< 200 ms (seek)		
Access Times	Full Stroke DVD	< 200 ms (seek)		
Disc Capacity	DVD-ROM	8.5 GB DL or 4.7 GB standard		
	CD-R CD-RW			
	DVD-RW			
	DVD-R			
	DVD-R DL			

HP 9.5mm Slim DVD-ROM	Description	9.5mm height, tray-load	
Drive	Mounting Orientation	Either horizontal or vertical	
	Interface Type	SATA / ATAPI	
	Dimensions (WxHxD)	128 x 9.5 x 127mm	
	Disc Capacity	DVD-ROM	Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB

hp

Access Times	DVD-ROM Single Layer	< 110 ms (typical)	
	CD-ROM Mode 1	< 110 ms (typical)	
	Full Stroke DVD	< 230 ms (typical)	
	Full Stroke CD	< 220 ms (typical)	
Power	Source	SATA DC power receptacle	
	DC Power Requirements	5 VDC ± 5%-100 mV ripple p-p	
	DC Current	5 VDC – <800mA typical, < 1600 mA maximum	
Operating Environmental	Temperature	41° to 122° F (5° to 50° C)	
(all conditions non-	Relative Humidity	10% to 80%	
condensing)	Maximum Wet Bulb Temperature	84° F (29° C)	
Operating Systems Supported	Windows 11, Windows 10, Windows 7 Professional 64-bit,		
	Windows Vista Business 64*, Windows 2000. Linux®.		
Kit Contents	9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation quide		
Approvals	USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transpo Specification Rev. 1.0,		
	Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE BSMI, C-Tick, VCCI, MIC, cUL, TUVT		
<b>NOTE:</b> Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.			



Integrated Intel® I219LM		RJ-45
PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.01)	Cabling	Twisted pair up to 100m
	Controller	Intel <sup>®</sup> I219LM GbE platform LAN connect networking controller
	Memory	3 KB Tx and 3KB Rx FIFO packet buffer memory
	Data Rates Supported	10/100/1000 Mbps
	Compliance	802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u, 802.3z
	Bus Architecture	PCI Express and SMBus
	Data Transfer Mode	PCIe-based interface for active state operation (S0 state) and SMBus for host and management traffic (Sx low power state)
	Power Requirement	Requires 3.3V (integrated regulators for core Vdc)
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps
	Management Capabilities	vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI, Advanced cable diagnostic, loopback modes, AMT 16.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)
	chipset, and network hard over a host OS-based VPN, powered off. Results depe	system with a corporate network connection, an Intel® AMT enabled ware and software. For notebooks, Intel AMT may be unavailable or limited , when connecting wirelessly, on battery power, sleeping, hibernating, or ndent upon hardware, setup, and configuration. For more information, visit: ntent/www/us/en/architecture-and-technology/intel-active-management-
HP 1-Port 1GbE Flex IO	Connector	RJ-45
NIC	Cabling	1GbE over Category 5e (or better) up to 100m
	Controller	Realtek RTL8153
	Data Rates Supported	10/100/1000 Mbps
	Compliance	802.3 (LAN) 802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control) 802.1Q (Virtual LAN) 802.3az (Energy Efficient Ethernet)
	Bus Architecture	USB
	Power Requirement	Requires 3.3V (integrated regulators for core Vdc)
	Boot ROM Support	Yes
	Network Transfer Mode	Full-duplex; Half-duplex
	Network Transfer Rate	10BASE-T (half-duplex) 10 Mbps 10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps



	Operating Temperature Dimensions (HxW) Operating System Driver Support	100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps 32° to 131° F (0° to 55° C) 1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm) Windows 11 64-bit Windows 10 64-bit Linux®	
Intel® X550-T2 2-Port 10GbE NIC	Connector Cabling	Dual-port RJ-45 10GbE: Cat6a (or better) up to 100m	
		5GbE and below: Cat5e (or better) up to 100m	
	Controller	Intel® Ethernet Controller X550	
	Network Transfer Rates Supported	10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE	
	Data Path Width	PCIe Gen3x4	
	Power Requirement	11.2W (typical) 13.0 (Maximum)	
	Operating Temperature	32° to 131° F (0° to 55° C)	
	Dimensions (HxW)	5.1 x 2.7 in (without brackets)	
	Operating System Driver Support	Windows 11 64-Bit Windows 10 64-bit Linux®	
	Kit Contents	<ul> <li>Intel® X550-T2 2-Port 10GbE NIC with standard height bracket attached</li> <li>Low-profile bracket</li> <li>Product Literature</li> </ul>	
NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Connector Cabling Controller Network Transfer Rates Supported	Dual-port SFP28 Transceiver with Multi-Mode Fiber OM3 or OM4) ConnectX-6 Dx 1/10/25 GbE	
	Data Path Width	PCIe Gen4x8	
	Power Requirement	19.74W Maximum power available through SFP28 port: 2.5W (each port)	
	Operating Temperature	32° to 131° F (0° to 55° C)	
	Dimensions (HxW)	6.22in. x 2.67in (158mm x 68mm)	
	Operating System Driver	Windows 11 64-Bit Windows 10 64-bit Linux®	
	Kit Contents	<ul> <li>NVIDIA Mellanox ConnectX-6 SFP28 25GbE NIC with standard height bracket attached</li> <li>Low-profile bracket</li> <li>Product Literature</li> </ul>	
	<b>NOTE:</b> The NVIDIA Mellanox ConnectX-6 DX network adapter requires either a PCIeG4 x4 or PCIeG4 x8 slot (electrical connection) to have full performance with two 25GbE SFP28 transceivers installed in the network adapter. When the network adapter is installed in a PCIeG3 x4 slot, the performance will		



be limited when installing two 25GbE SFP28 transceivers or installing a 25GbE SFP28 transceiver plus a 10GbE SFP+ transceiver

Intel® 1350-T4 4-Port	Connector	4 RJ-45		
1GbE NIC	Cabling	Cat5e (or better) up to 100m		
	Controller	Intel® Ethernet I350 Controller		
	Network Transfer Rates Supported	1GbE, 100MbE, 10MbE		
	Data Path Width	PCIe Gen2.1x4		
	Power Requirement	5W (typical) 32° to 131° F (0° to 55° C)		
	<b>Operating Temperature</b>			
	Dimensions (HxW)	2.75 x 5.5 inches (without brackets)		
	<b>Operating System Driver</b>	Windows 11		
	Support	Windows 10		
	Kit Contents	<ul> <li>Intel<sup>®</sup> I350-T4 4-Port 1GbE NIC with standard height bracket attached</li> <li>Low-profile bracket</li> <li>Product Literature</li> </ul>		
HP Flex 1GbE Fiber LC	Connector	Fiber		
Single Port	Cabling	1GbE over Category OM1 (or better) up to 100m		
	Controller	Microchip LAN7801		
	Data Rates Supported	100/1000 Mbps		
	Compliance	IEEE 802.1p priority encoding/tagging (QoS, CoS) IEEE 802.1q VLAN tagging IEEE 802.3x flow control		
	Bus Architecture	USB		
	Power Requirement	Requires 3.3V (integrated regulators for core Vdc)		
	Boot ROM Support	Yes		
	Network Transfer Mode	Full-duplex; Half-duplex		
	Network Transfer Rate	100BASE-X (half-duplex) 100 Mbps 1000BASE-X (half-duplex) 1000 Mbps 1000BASE-X (full-duplex) 2000 Mbps		
	<b>Operating Temperature</b>	32° to 158° F (0°C to 70°C)		
	calvin	1.5 in x 1.7 in. x 0.75 in (3.84 cm x 4.3 cm x 1.9 cm)		
	Operating System Driver Support	Windows 11 64-Bit Windows 10 64-bit Linux®		
Intel® I225-T1 1-Port	Connector	RJ-45		
2.5GbE NIC	Cabling	Cat5e (or better) up to 85m		
	Controller	Intel <sup>®</sup> Ethernet I225 Controller		
	Network Transfer Rates Supported	2.5GbE, 1GbE, 100MbE, 10MbE		

	Data Path Width	PCIe Gen3.1x1	
Power Requirement		1.9W (typical)	
	Operating Temperature	32° to 158° F (0°C to 70°C)	
	Dimensions (HxW)	2.7 in x 2.57 in. (68.7mm x 65.3mm)	
	Operating System Driver	Windows 11 64-Bit Windows 10 64-bit Linux®	
	Kit Contents	<ul> <li>Intel<sup>®</sup> I225-T1 1-Port 2.5GbE NIC with standard height bracket attached Low-profile bracket</li> <li>Product Literature</li> </ul>	
Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 With Internal Antenna	WLAN Standards	802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E	
	Antenna	2x2 Dual-Band (internal)	
	<b>Bluetooth Standards</b>	5.2	
	Operating Temperature	32° to 176° F (0° to 80° C)	
	Interface	M.2 CNVio2	
	Dimensions	M.2 2230	
		Not Available ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public	
	<b>NOTE:</b> The AX211 with int *Wi-Fi 6E requires a Wi-Fi	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available	
Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 With External Antenna	<b>NOTE:</b> The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available	
802.11ax, BT 5.3, M.2	<b>NOTE:</b> The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2,	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External)	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards Operating Temperature	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C)	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards Operating Temperature Interface	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available	
802.11ax, BT 5.3, M.2	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported.	
802.11ax, BT 5.3, M.2 With External Antenna	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2+be+dehikrv 2x2 Dual-Band (External)	
802.11ax, BT 5.3, M.2 With External Antenna	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2+be+dehikrv 2x2 Dual-Band (External) 5.4	
802.11ax, BT 5.3, M.2 With External Antenna	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2+be+dehikrv 2x2 Dual-Band (External)	
802.11ax, BT 5.3, M.2 With External Antenna	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2+be+dehikrv 2x2 Dual-Band (External) 5.4	
802.11ax, BT 5.3, M.2 With External Antenna	NOTE: The AX211 with int *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Operating Temperature Interface Dimensions Kit Contents NOTE: The AX211 with ext *Wi-Fi 6E requires a Wi-Fi wireless access points lim in countries where Wi-Fi 6 WLAN Standards Antenna Bluetooth Standards Operating Temperature	ernal antenna only support WIFI 6 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2 High performance, low power dual band Pre-Standard-802.11ax R2 2x2, both with 160MHz channel support – Wi-Fi 6E 2x2 Dual-Band (External) 5.2 32° to 176° F (0° to 80° C) M.2 CNVio2 M.2 2230 ANTENNA, External, Dipole, WLAN, WIFI 6E ternal antenna support WIFI 6E 6E router, sold separately, to function in the 6GHz band. Availability of public ited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available E is supported. 802.11abgn+acR2+axR2+be+dehikrv 2x2 Dual-Band (External) 5.4 32° to 176° F (0° to 80° C)	

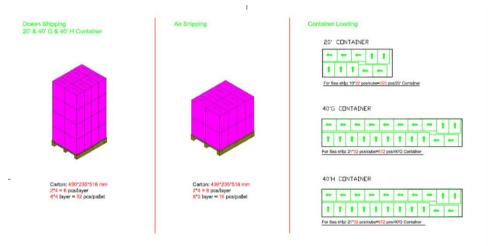


**NOTE:** Not available with 12th Gen Intel ADL processors; Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 7 (802.11BE) functionality requires Windows 11 24H2, select Intel® processor, and a Wi-Fi 7 router, sold separately. Wi-Fi 7 is backwards compatible with prior 802.11 specs. Available in countries where Wi-Fi 7 is supported.

### Palletization

Ocean Shipping uses a 20' x 40' x 40' (490mm x 295mm x 518mm) container with 4 layers; 2x4=8 pieces per layer for a total of 32 pieces per pallet

Air shipping uses 490mm x 295mm x 518mm carton with 2 layers; 2x4=8 pieces per layer for a total of 16 pieces per pallet.



Date of change:	Version History:		Description of change:
March 8, 2022	From v1 to v2	Changed	Format
March 16, 2022	From v2 to v3	Changed	Social and Environmental Responsibility section
May 6, 2022	From v3 to v4	Changed	Processors, Graphics, Networking and Communications sections
June 1, 2022	From v4 to v5	Changed	Operating Systems and SATA Hard Drives sections
June 15, 2022	From v5 to v6	Changed	Networking and Communications section
July 1, 2022	From v6 to v7	Changed	Graphics section
July 8, 2022	From v7 to v8	Changed	System Board section
August 1, 2022	From v8 to v9	Changed	SATA Hard Drives, Other Hardware sections
August 4, 2022	From v9 to v10	Changed	Format
September 1, 2022	From v10 to v11	Changed	Storage / Hard Drives, Graphics, Optical and Removable Storage
			Networking and Communications sections
October 1, 2022	From v11 to v12	Changed	Graphics, Networking and Communications sections
November 1, 2022	From v12 to v13	Changed	Graphics Adapters section
February 6, 2023	From v13 to v14	Changed	Processors section
March 1, 2023	From v14 to v15	Changed	Manageability section
March 30, 2023	From v15 to v16	Changed	Processors section
April 25, 2023	From v16 to v17	Changed	Power Supply, Social and Environmental Responsibility sections
May 1, 2023	From v17 to v18	Changed	Other Hardware section
June 1, 2023	From v18 to v19	Changed	Graphics, Social and Environmental Responsibility, Palletization
			sections
July 1, 2023	From v19 to v20	Changed	Networking and Communications, Other Hardware, HP BIOS sections
July 5, 2023	From v20 to v21	Changed	System Board section
August 1, 2023	From v21 to v22	Changed	Social and Environmental Responsibility section
August 1, 2023	From v22 to v23	Changed	ENVIRONMENTAL DATA section



September 15, 2023	From v23 to v24	Changed	Networking and Communications
October 1, 2023	From v24 to v25	Changed	Graphics, Input Devices sections
November 1, 2023	From v25 to v26	Changed	Graphics, Input Devices sections
December 1, 2023	From v26 to v27	Changed	Graphics, Other Hardware, Social and Environmental Responsibility
			sections
December 11, 2023	From v27 to v28	Changed	Optical and Removable Storage section
December 21, 2023	From v28 to v29	Changed	Graphics section
February 1, 2024	From v29 to v30	Changed	Social and Environmental Responsibility section
March 1, 2024	From v30 to v31	Changed	Graphics, System Configurations, Declared Noise Emissions and
			Networking and Communications sections
March 12, 2024	From v31 to v32	Changed	Processors section
April 1, 2024	From v32 to v33	Changed	Graphics and Other Hardware sections
May 1, 2024	From v33 to v34	Changed	Graphics, Social and Environmental Responsibility sections
June 1, 2024	From v34 to v35	Changed	Storage section
July 1, 2024	From v35 to v36	Changed	Graphics, Memory, Networking and Communications sections
July 18, 2024	From v36 to v37	Changed	Software section
August 1, 2024	From v37 to v38	Changed	Graphics, Memory sections
August 1, 2024	From v38 to v39	Changed	Graphics section



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